

**PATENT ASSIGNMENT**

Electronic Version v08  
 Stylesheet Version v02

SUBMISSION TYPE:		NEW ASSIGNMENT	<b>APPLICATION NUMBER</b> 11/309540		
NATURE OF CONVEYANCE:		ASSIGNMENT OF ASSIGNOR'S INTEREST			
CONVEYING PARTY DATA					
Name		Execution Date			
MING-CHIH HSIEH		2006-08-11			
RECEIVING PARTY DATA					
Name	Street Address	Internal Address	City	State/Country	Postal Code
HON HAI PRECISION INDUSTRY CO., LTD.	66,CHUNG SHAN ROAD		Tu-Cheng, Taipei Hsien	TAIWAN	
CORRESPONDENCE DATA					
FAX NUMBER: 7147384649					
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>					
When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.					
CUSTOMER NUMBER: 054000					
NAME OF PERSON SIGNING:		WEI TE CHUNG			
DATE SIGNED:		2006-08-19			
Total Attachments: 2 source=US9248assign1.tif source=US9248assign2.tif					

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## ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

- |    |                        |               |                                 |
|----|------------------------|---------------|---------------------------------|
| 1. | <u>Ming-Chih Hsieh</u> | , residing at | <u>Tu-cheng, Taipei, Taiwan</u> |
| 2. | _____                  | , residing at | _____                           |
| 3. | _____                  | , residing at | _____                           |
| 4. | _____                  | , residing at | _____                           |
| 5. | _____                  | , residing at | _____                           |
| 6. | _____                  | , residing at | _____                           |
| 7. | _____                  | , residing at | _____                           |
| 8. | _____                  | , residing at | _____                           |

hereby sell(s), assign(s) and transfer(s) unto: Hon Hai Precision Ind. Co., LTD having a principal place of business at 66 Chung Shan Road, Tu-Cheng City, Taipei Hsien, Taiwan, R.O.C. hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as SURFACE-MOUNT PACKAGING FOR CHIP for which the undersigned

[     ] previously executed --- Ser. No. \_\_\_\_\_ and filing date of \_\_\_\_\_

[ x ] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

**PATENT**

**REEL: 018141 FRAME: 0110**

